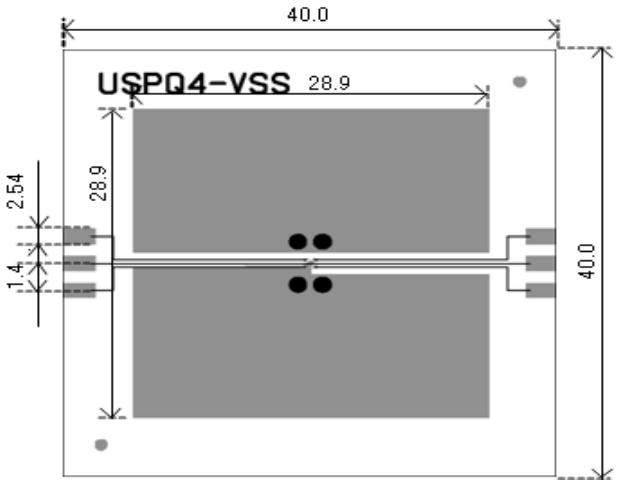
● USPQ-4B03 Power Dissipation

Power dissipation data for the USPQ-4B03 is shown in this page.
The value of power dissipation varies with the mount board conditions.
Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition:	Mount on a board
Ambient:	Natural convection
Soldering:	Lead (Pb) free
Board Dimensions:	40 x 40 mm (1600mm2)
Board Structure:	4 Copper Layers
	Each layer is connected to the package heat-sink
	and terminal pin No.1.
	Each layer has approximately 800mm2 copper ar
Material:	Glass Epoxy (FR-4)
Thickness:	1.6 mm
Through-hole:	4 x 0.8 Diameter



Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient Temperature

Board Mount (Tj max = 125℃)

Ambient Temperature(℃)	Power Dissipation Pd(mW)	Thermal Resistance(℃/W)
25	550	181.82
85	220